

NP35N04YLG

MOS FIELD EFFECT TRANSISTOR

R07DS0182EJ0100 Rev.1.00 Oct 22, 2010

Description

The NP35N04YLG is N-channel MOS Field Effect Transistor designed for high current switching applications.

Features

- Low on-state resistance
 - --- $R_{DS(on)}$ = 9.7 mΩ MAX. (V_{GS} = 10 V, I_D = 17.5 A)
 - --- $R_{DS(on)}$ = 15 mΩ MAX. (V_{GS} = 5 V, I_D = 17.5 A)
- Logic level drive type
- Gate to Source ESD protection diode built in
- Designed for automotive application and AEC-Q101 qualified

Ordering Information

Part No.	LEAD PLATING	PACKING	Package
NP35N04YLG -E1-AY *1	Pure Sn (Tin)	Tape 2500 p/reel	8-pin HSON, Taping (E1 type)
NP35N04YLG -E2-AY *1			8-pin HSON, Taping (E2 type)

Note: *1. Pb-free (This product does not contain Pb in the external electrode.)

Absolute Maximum Ratings ($T_A = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V _{GS} = 0 V)	V _{DSS}	40	V
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±20	V
Drain Current (DC) (T _C = 25°C)	I _{D(DC)}	±35	А
Drain Current (pulse) *1	I _{D(pulse)}	±105	Α
Total Power Dissipation (T _C = 25°C)	P _{T1}	77	W
Total Power Dissipation ($T_A = 25^{\circ}C$) *2	P _{T2}	1.0	W
Channel Temperature	T _{ch}	175	°C
Storage Temperature	T _{stg}	−55 to +175	°C
Repetitive Avalanche Current *3	I _{AR}	22	А
Repetitive Avalanche Energy *3	E _{AR}	48	mJ

Thermal Resistance

Channel to Case Thermal Resistance $R_{th(ch-C)}$ 1.95 °C/W Channel to Ambient Thermal Resistance *2 $R_{th(ch-A)}$ 150 °C/W

Notes: *1. $T_C = 25^{\circ}C$, $PW \le 10 \mu s$, Duty Cycle $\le 1\%$

*2. Mounted on glass epoxy substrate of 40 mm x 40 mm x 0.8 mmt

*3. $T_{ch(peak)} \le 150^{\circ}C$, $R_G = 25 \Omega$

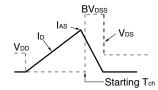
Electrical Characteristics (T_A = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Zero Gate Voltage Drain Current	I _{DSS}			1	μΑ	V _{DS} = 40 V, V _{GS} = 0 V
Gate Leakage Current	I _{GSS}			±10	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to Source Threshold Voltage	$V_{GS(th)}$	1.4	1.9	2.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$
Forward Transfer Admittance *1	y _{fs}	15	30		S	$V_{DS} = 5 \text{ V}, I_{D} = 17.5 \text{ A}$
Drain to Source On-state Resistance *1	R _{DS(on)1}		7.8	9.7	mΩ	V _{GS} = 10 V, I _D = 17.5 A
Drain to Source On-state Resistance *1	R _{DS(on)2}		9.6	15	mΩ	$V_{GS} = 5 \text{ V}, I_D = 17.5 \text{ A}$
Input Capacitance	C _{iss}		1900	2850	pF	V _{DS} = 25 V,
Output Capacitance	Coss		190	290	pF	$V_{GS} = 0 V$,
Reverse Transfer Capacitance	C _{rss}		120	220	pF	f = 1 MHz
Turn-on Delay Time	$t_{d(on)}$		13	26	ns	$V_{DD} = 20 \text{ V}, I_D = 17.5 \text{ A},$
Rise Time	t _r		11	27	ns	$V_{GS} = 10 V$,
Turn-off Delay Time	$t_{d(off)}$		43	86	ns	$R_G = 0 \Omega$
Fall Time	t _f		5	12	ns	
Total Gate Charge	Q_G		34	51	nC	V _{DD} = 32 V,
Gate to Source Charge	Q_{GS}		6		nC	V_{GS} = 10 V ,
Gate to Drain Charge	Q_{GD}		10		nC	I _D = 35 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$		0.91	1.5	V	I _F = 35 A, V _{GS} = 0 V
Reverse Recovery Time	t _{rr}		27		ns	I _F = 35 A, V _{GS} = 0 V,
Reverse Recovery Charge	Q _{rr}		25		nC	$di/dt = 100 A/\mu s$

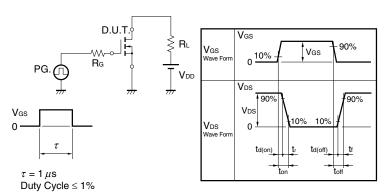
Note: *1. Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

$V_{GS} = 20 \rightarrow 0 \text{ V}$ $PG. \qquad PG. \qquad PG. \qquad V_{DD}$ $PG. \qquad V_{DD}$ $PG. \qquad V_{DD}$ $PG. \qquad PG. \qquad P$



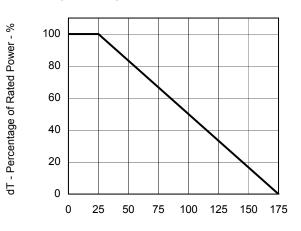
TEST CIRCUIT 2 SWITCHING TIME



TEST CIRCUIT 3 GATE CHARGE

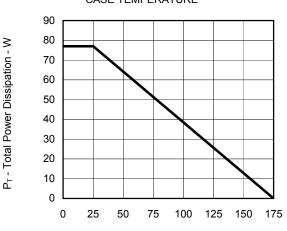
Typical Characteristics ($T_A = 25^{\circ}C$)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



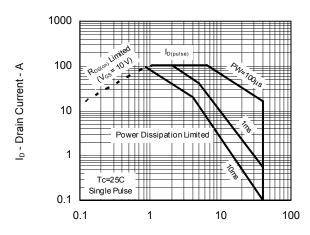
T_C - Case Temperature - °C

TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



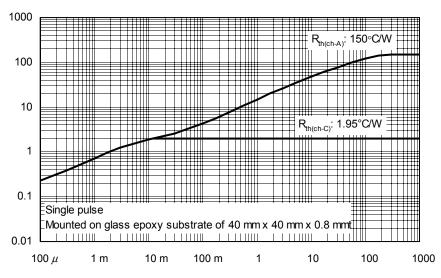
T_C - Case Temperature - °C

FORWARD BIAS SAFE OPERATING AREA



 V_{DS} - Drain to Source Voltage - V

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

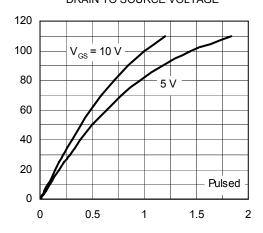


PW - Pulse Width - s

I_D - Drain Current - A

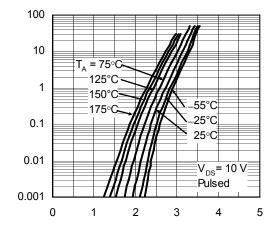
V_{GS(th)} - Gate to Source Threshold Voltage - V

DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



 V_{DS} - Drain to Source Voltage - V

FORWARD TRANSFER CHARACTERISTICS

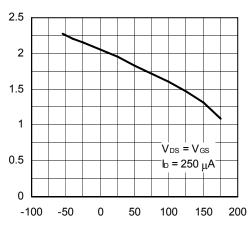


I_D - Drain Current - A

| y_{fs} | - Forward Transfer Admittance - S

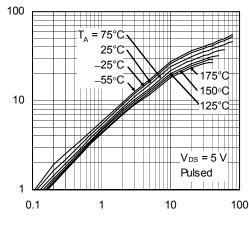
V_{GS} - Gate to Source Voltage - V

GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



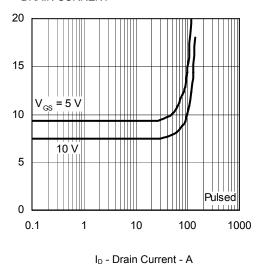
T_{ch} - Channel Temperature - °C

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

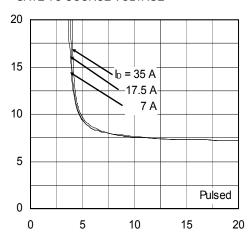


I_D - Drain Current - A

DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



V_{GS} - Gate to Source Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

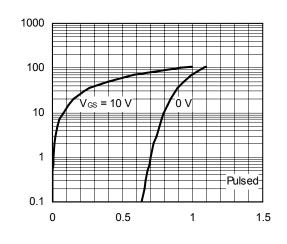
t_{d(on)}, t_r, t_{d(off)}, t_f - Switching Time - ns

IF - Diode Forward Current - A

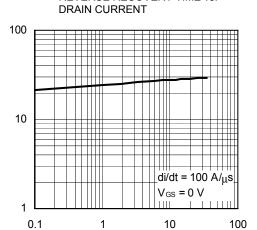
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE CHANNEL TEMPERATURE 10000 25 $I_D = 17.5 A$ Ciss, Coss, Crss - Capacitance - pF Pulsed 20 $V_{GS} = 5 V$ 1000 15 10 V 10 100 5 $V_{GS} = 0 V_{-}$ f = 1MHz10 0 10 -50 0.1 -100 0 50 100 150 200 V_{DS} - Drain to Source Voltage - V T_{ch} - Channel Temperature - °C SWITCHING CHARACTERISTICS DYNAMIC INPUT/OUTPUT CHARACTERISTICS 1000 40 V_{DD} = 20 V V_{DS} - Drain to Source Voltage - V V_{GS} = 10 V 35 $R_G = 0 \Omega$ $V_{DD} = 32 \text{ V}$ 30 100 25 t_{d(off} 20 15 10 10 5 0 1 0 10 20 0.1 10 100

SOURCE TO DRAIN DIODE FORWARD VOLTAGE

I_D - Drain Current - A



 $V_{F(S-D)}$ - Source to Drain Voltage - V



Q_G - Gate Charge - nC

REVERSE RECOVERY TIME vs.

I_F - Drain Current - A

100

12

10

8

6

4

2

0

40

V_{GS} - Gate to Source Voltage - V

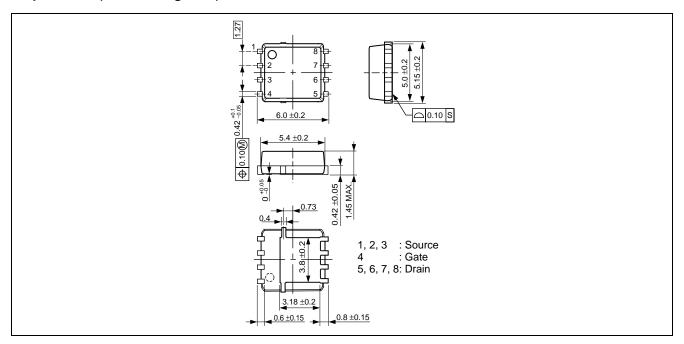
lo = 35 A

30

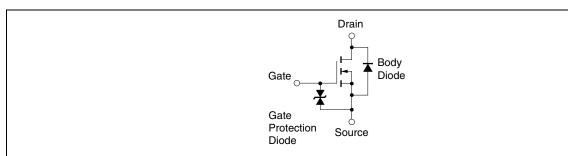
t_{rr} - Reverse Recovery Time - ns

Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)



Equivalent Circuit



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Revision History NP35N04YLG

		Description		
Rev.	Date	Page Summary		
1.00	Oct 22, 2010	-	First Edition Issued	

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